



# Section 1

## Basic Phenomena of Electronics

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# Section 2

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# Circuit Principles

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<sup>1</sup>The author acknowledges with gratitude the contributions of the late Professor Everard M. Williams to this section of the "Handbook" in the first edition, on which this revision is in part based.

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# Information, Communication, Noise, and Interference

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# Systems Engineering

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*Since everything, then, is cause and effect, dependent and supporting, mediate and immediate, and all is held together by a natural though imperceptible chain which binds together things most distant and most different, I hold it equally impossible to know the parts without knowing the whole and to know the whole without knowing the parts in detail.*

— PASCAL, "Pensées," No. 72

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# Properties of Materials

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# UHF and Microwave Devices

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# Transducers and Sensors\*

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# Filters and Attenuators\*

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# Section 15

## Power Electronics

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# Pulsed Circuits, Logic Circuits, and Waveform Generators

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# Section 17

## Measurement and Control Circuits

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# Section 18

## Antennas and Wave Propagation

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# Sound Reproduction and Recording Systems

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# Section 20

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# Broadcasting Systems

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# Electronic Data Processing

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# Section 27

## Computer-Aided Design of Electronic Circuits

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**1. Introduction.** Circuit designers of previous generations found it necessary to build breadboards, fit them with worst-case or limit devices, i.e., active devices whose characteristics were at the high or low specification limits, and then see whether the circuit performed satis-

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